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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	F²MC-16LX
Core Size	16-Bit
Speed	16MHz
Connectivity	CANbus, SCI, UART/USART
Peripherals	POR, WDT
Number of I/O	36
Program Memory Size	64KB (64K x 8)
Program Memory Type	Mask ROM
EEPROM Size	-
RAM Size	2K x 8
Voltage - Supply (Vcc/Vdd)	3.5V ~ 5.5V
Data Converters	A/D 8x8/10b
Oscillator Type	External
Operating Temperature	-40°C ~ 105°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/infineon-technologies/mb90387spmt-gt-106

1. Product Lineup

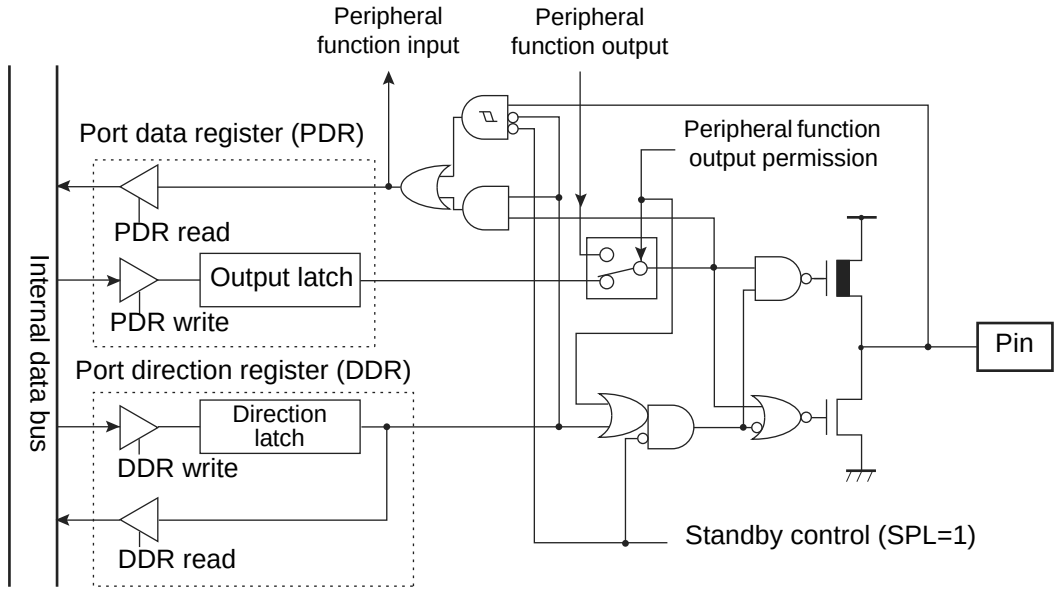
Parameter \ Part Number		MB90F387 MB90F387S	MB90387 MB90387S	MB90V495G
Classification		Flash ROM	Mask ROM	Evaluation product
ROM capacity		64 Kbytes		–
RAM capacity		2 Kbytes		6 Kbytes
Process		CMOS		
Package		LQFP-48 (pin pitch 0.50 mm)		PGA-256
Operating power supply voltage		3.5 V to 5.5 V		4.5 V to 5.5 V
Special power supply for emulator*1		–		None
CPU functions		Number of basic instructions : 351 instructions Instruction bit length : 8 bits and 16 bits Instruction length : 1 byte to 7 bytes Data bit length : 1 bit, 8 bits, 16 bits		
		Minimum instruction execution time: 62.5 ns (at 16 MHz machine clock)		
		Interrupt processing time: 1.5 μs at minimum (at 16 MHz machine clock)		
Low power consumption (standby) mode		Sleep mode / Watch mode / Time-base timer mode / Stop mode / CPU intermittent		
I/O port		General-purpose input/output ports (CMOS output): 34 ports (36 ports*2) including 4 high-current output ports (P14 to P17)		
Time-base timer		18-bit free-run counter Interrupt cycle: 1.024 ms, 4.096 ms, 16.834 ms, 131.072 ms (with oscillation clock frequency at 4 MHz)		
Watchdog timer		Reset generation cycle: 3.58 ms, 14.33 ms, 57.23 ms, 458.75 ms (with oscillation clock frequency at 4 MHz)		
16-bit input/ output timer	16-bit free-run timer	Number of channels: 1 Interrupt upon occurrence of overflow		
	Input capture	Number of channels: 4 Retaining free-run timer value set by pin input (rising edge, falling edge, and both edges)		
16-bit reload timer		Number of channels: 2 16-bit reload timer operation Count clock cycle: 0.25 μs, 0.5 μs, 2.0 μs (at 16-MHz machine clock frequency) External event count is allowed.		
Watch timer		15-bit free-run counter Interrupt cycle: 31.25 ms, 62.5 ms, 12 ms, 250 ms, 500 ms, 1.0 s, 2.0 s (with 8.192 kHz sub clock)		
8/16-bit PPG timer		Number of channels: 2 (four 8-bit channels are available also.) PPG operation is allowed with four 8-bit channels or two 16-bit channels. Outputting pulse wave of arbitrary cycle or arbitrary duty is allowed. Count clock: 62.5 ns to 1 μs (with 16 MHz machine clock)		
Delay interrupt generator module		Interrupt generator module for task switching. Used for realtime OS.		
DTP/External interrupt		Number of inputs: 4 Activated by rising edge, falling edge, “H” level or “L” level input. External interrupt or expanded intelligent I/O service (EI^{2}OS) is available.		

10. I/O Map

Address	Register Abbreviation	Register	Read/ Write	Resource	Initial Value
000000H	(Reserved area) *				
000001H	PDR1	Port 1 data register	R/W	Port 1	XXXXXXXXB
000002H	PDR2	Port 2 data register	R/W	Port 2	XXXXXXXXB
000003H	PDR3	Port 3 data register	R/W	Port 3	XXXXXXXXB
000004H	PDR4	Port 4 data register	R/W	Port 4	XXXXXXXXB
000005H	PDR5	Port 5 data register	R/W	Port 5	XXXXXXXXB
000006H to 000010H	(Reserved area) *				
000011H	DDR1	Port 1 direction data register	R/W	Port 1	00000000B
000012H	DDR2	Port 2 direction data register	R/W	Port 2	00000000B
000013H	DDR3	Port 3 direction data register	R/W	Port 3	000X0000B
000014H	DDR4	Port 4 direction data register	R/W	Port 4	XXX00000B
000015H	DDR5	Port 5 direction data register	R/W	Port 5	00000000B
000016H to 00001AH	(Reserved area) *				
00001BH	ADER	Analog input permission register	R/W	8/10-bit A/D converter	11111111B
00001CH to 000025H	(Reserved area) *				
000026H	SMR1	Serial mode register 1	R/W	UART1	00000000B
000027H	SCR1	Serial control register 1	R/W, W		00000100B
000028H	SIDR1/ SODR1	Serial input data register 1/ Serial output data register 1	R, W		XXXXXXXXB
000029H	SSR1	Serial status data register 1	R, R/W		00001000B
00002AH	(Reserved area) *				
00002BH	CDCR1	Communication prescaler control register 1	R/W	UART1	0XXX0000B
00002CH to 00002FH	(Reserved area) *				
000030H	ENIR	DTP/External interrupt permission register	R/W	DTP/External interrupt	00000000B
000031H	EIRR	DTP/External interrupt permission register	R/W		XXXXXXXXB
000032H	ELVR	Detection level setting register	R/W		00000000B
000033H			R/W		00000000B
000034H	ADCS	A/D control status register	R/W	8/10-bit A/D converter	00000000B
000035H			R/W, W		00000000B
000036H	ADCR	A/D data register	W, R		XXXXXXXXB
000037H			R		00101XXXB

Address	Register Abbreviation	Register	Read/ Write	Resource	Initial Value
000083H	(Reserved area) *				
000084H	TCANR	Send cancel register	W	CAN controller	00000000B
000085H	(Reserved area) *				
000086H	TCR	Send completion register	R/W	CAN controller	00000000B
000087H	(Reserved area) *				
000088H	RCR	Receive completion register	R/W	CAN controller	00000000B
000089H	(Reserved area) *				
00008AH	RRTRR	Receive RTR register	R/W	CAN controller	00000000B
00008BH	(Reserved area) *				
00008CH	ROVRR	Receive overrun register	R/W	CAN controller	00000000B
00008DH	(Reserved area) *				
00008EH	RIER	Receive completion interrupt permission register	R/W	CAN controller	00000000B
00008FH to 00009DH	(Reserved area) *				
00009EH	PACSR	Address detection control register	R/W	Address matching detection function	00000000B
00009FH	DIRR	Delay interrupt request generation/ release register	R/W	Delay interrupt generation module	XXXXXXX0B
0000A0H	LPMCR	Lower power consumption mode control register	W,R/W	Lower power consumption mode	00011000B
0000A1H	CKSCR	Clock selection register	R,R/W	Clock	11111100B
0000A2H to 0000A7H	(Reserved area) *				
0000A8H	WDTC	Watchdog timer control register	R,W	Watchdog timer	XXXXX111B
0000A9H	TBTC	Time-base timer control register	R/W,W	Time-base timer	1XX00100B
0000AAH	WTC	Watch timer control register	R,R/W	Watch timer	1X001000B
0000ABH to 0000ADH	(Reserved area) *				
0000AEH	FMCS	Flash memory control status register	R,W,R/W	512k-bit Flash memory	000X0000B
0000AFH	(Reserved area) *				

Port 2 Pins Block Diagram (general-purpose input/output port)



Standby control: Control among Stop mode (SPL=1), Time-base timer mode (SPL=1), and watch mode (SPL=1).

Port 2 Registers

■ Port 2 registers include port 2 data register (PDR2) and port 2 direction register (DDR2).

■ The bits configuring the register correspond to port 2 pins on a one-to-one basis.

Relation between Port 2 Registers and Pins

Port Name	Bits of Register and Corresponding Pins									
Port 2	PDR2,DDR2	bit7	bit6	bit5	bit4	bit3	bit2	bit1	bit0
	Corresponding pins	P27	P26	P25	P24	P23	P22	P21	P20

12.3 Watchdog Timer

The watchdog timer is a 2-bit counter that uses time-base timer or watch timer as count clock. If the counter is not cleared within an interval time, CPU is reset.

Watchdog Timer Functions

- The watchdog timer is a timer counter that prevents runaway of a program. Once a watchdog timer is activated, the counter of watchdog timer must always be cleared within a specified time of interval. If specified interval time elapses without clearing the counter of a watchdog timer, CPU resetting occurs. This is the function of a watchdog timer.
- The interval time of a watchdog timer is determined by a clock cycle, which is input as a count clock. Watchdog resetting occurs between a minimum time and a maximum time specified.
- The output target of a clock source is specified by the watchdog clock selection bit (WTC: WDCS) in the watch timer control register.
- Interval time of a watchdog timer is specified by the time-base timer output selection bit / watch timer output selection bit (WDTC: WT1, WT0) in the watchdog timer control register.

Interval Timer of Watchdog Timer

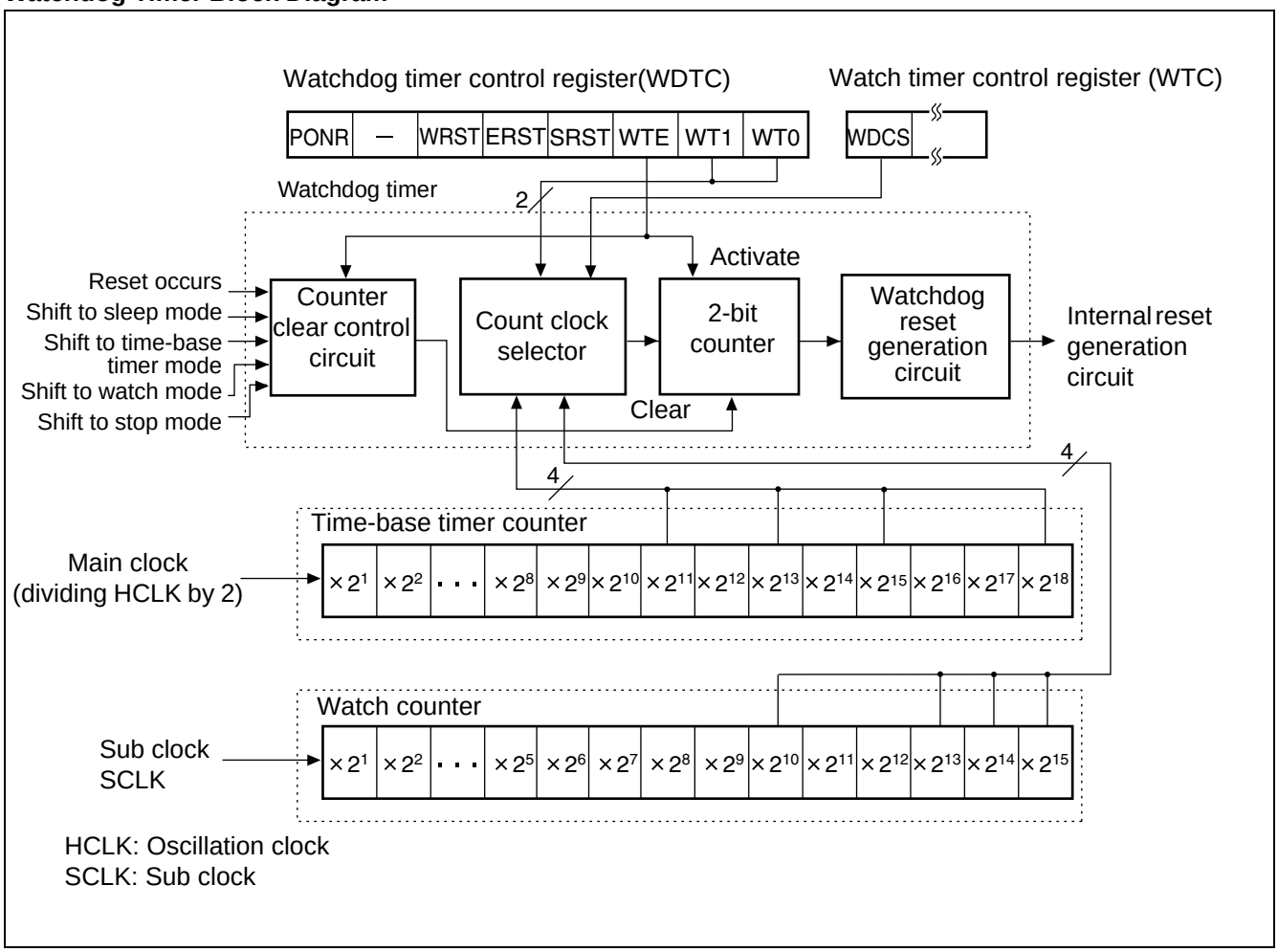
Min	Max	Clock Cycle	Min	Max	Clock Cycle
Approx. 3.58 ms	Approx. 4.61 ms	$(2^{14}\pm2^{11})$ /HCLK	Approx. 0.457 s	Approx. 0.576 s	$(2^{12}\pm2^{9})$ /SCLK
Approx. 14.33 ms	Approx. 18.3 ms	$(2^{16}\pm2^{13})$ /HCLK	Approx. 3.584 s	Approx. 4.608 s	$(2^{15}\pm2^{12})$ /SCLK
Approx. 57.23 ms	Approx. 73.73 ms	$(2^{18}\pm2^{15})$ /HCLK	Approx. 7.168 s	Approx. 9.216 s	$(2^{16}\pm2^{13})$ /SCLK
Approx. 458.75 ms	Approx. 589.82 ms	$(2^{21}\pm2^{18})$ /HCLK	Approx. 14.336 s	Approx. 18.432 s	$(2^{17}\pm2^{14})$ /SCLK

HCLK: Oscillation clock (4 MHz), CSCLK: Sub clock (8.192 kHz)

Notes:

- If the time-base timer is cleared when watchdog timer count clock is used as time base timer output (carry-over signal), watchdog reset time may become longer.
- When using the sub clock as machine clock, be sure to specify watchdog timer clock source selection bit (WDCS) in watch timer control register (WTC) at “0,” selecting output of watch timer.

Watchdog Timer Block Diagram



12.6 Watch Timer Outline

The watch timer is a 15-bit free-run counter that increments in synchronization with sub clock.

- Interval time is selectable among 7 choices, and generation of interrupt request is allowed for each interval.
- Provides operation clock to the subclock oscillation stabilizing wait timer and watchdog timer.
- Always uses subclock as a count clock regardless of settings of clock selection register (CKSCR).

Interval Timer Function

- In the watch timer, a bit corresponding to the interval time overflows (carry-over) when an interval time, which is specified by interval time selection bit, is reached. Then overflow flag bit is set (WTC: WTOF=1).
- If an interrupt by overflow is permitted (WTC: WTIE=1), an interrupt request is generated upon setting an overflow flag bit.
- Interval time of watch timer is selectable among the following seven choices:

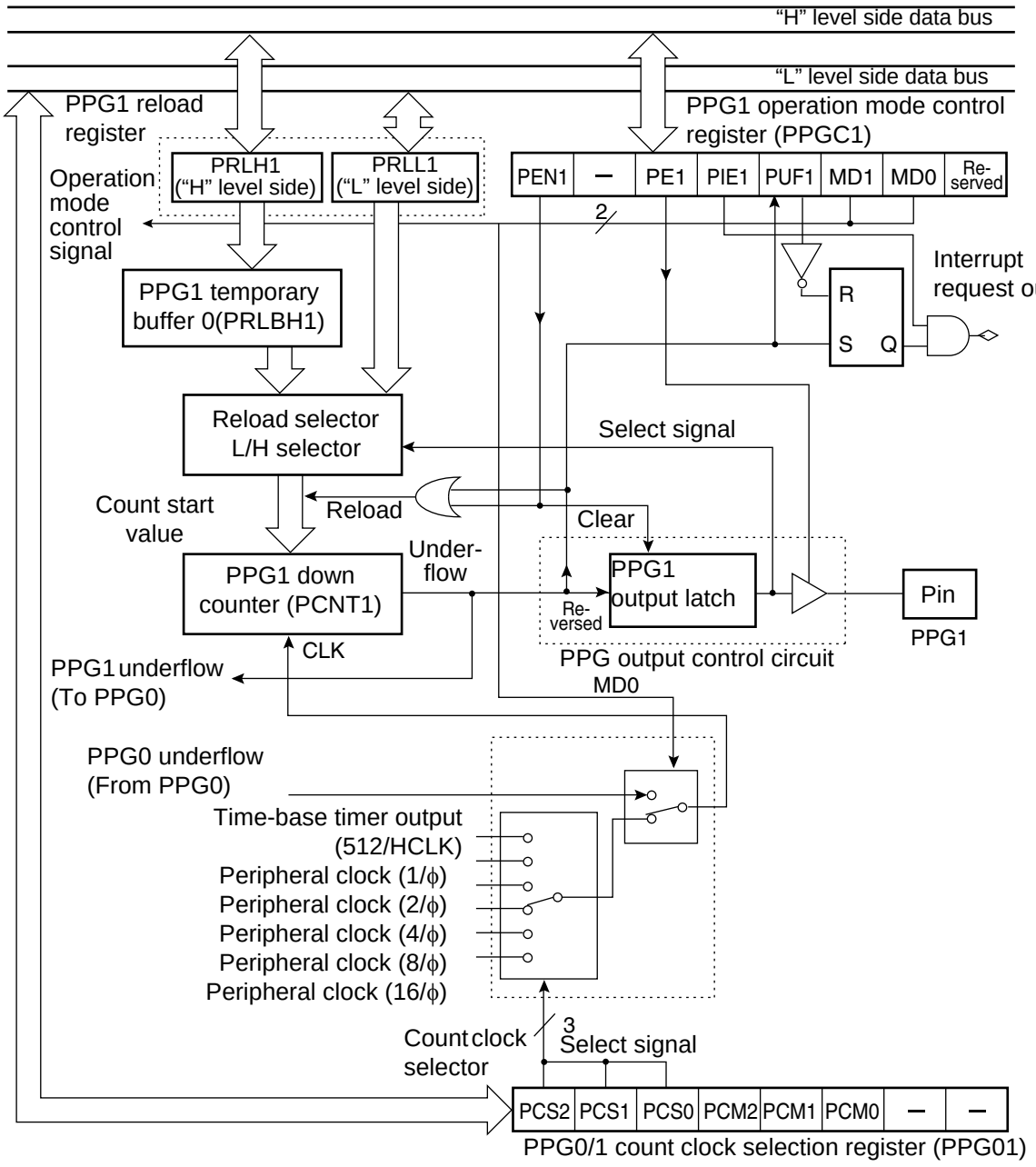
Interval Time of Watch Timer

Sub Clock Cycle	Interval Time
1/SCLK (122 μs)	2^8/SCLK (31.25 ms)
	2^9/SCLK (62.5 ms)
	2^{10}/SCLK (125 ms)
	2^{11}/SCLK (250 ms)
	2^{12}/SCLK (500 ms)
	2^{13}/SCLK (1.0 s)
	2^{14}/SCLK (2.0 s)

SCLK: Sub clock frequency

Values in parentheses “( )” are calculation when operating with 8.192 kHz clock.

8/16-bit PPG Timer 1 Block Diagram



– : Undefined
Reserved: Reserved bit
HCLK : Oscillation clock frequency
ϕ : Machine clock frequency
* : Interrupt output of 8/16-bit PPG timer 1 is incorporated into one by the OR circuit against interrupt output of 8/16-bit PPG timer 0.

12.12 CAN Controller

The Controller Area Network (CAN) is a serial communication protocol compliant with CANVer2.0A and Ver2.0B. The protocol allows data transmission and reception in both standard frame format and expanded frame format.

Features of CAN Controller

- CAN controller format is compliant with CANVer2.0A and Ver2.0B.
- The protocol allows data transmission and reception in standard frame format and expanded frame format.
- Automatic transmission of data frame by remote frame reception is allowed.
- Baud rate ranges from 10 kbps to 1 Mbps (with 16-MHz machine clock).

Table 12-5. Data Transmission Baud Rate

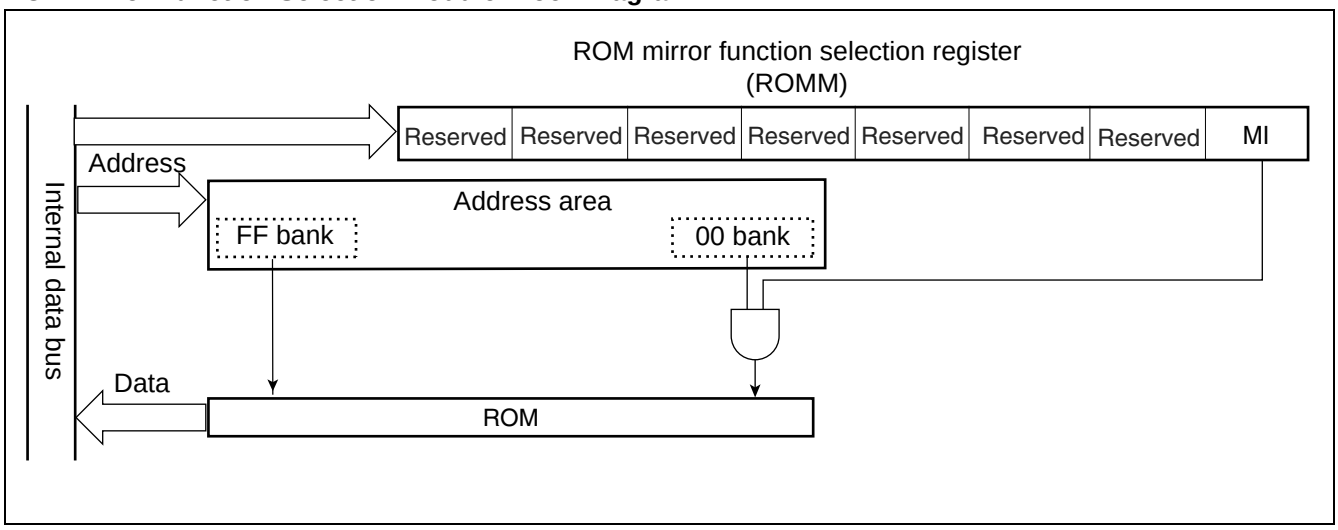
Machine Clock	Baud Rate (Max)
16 MHz	1 Mbps
12 MHz	1 Mbps
8 MHz	1 Mbps
4 MHz	500 kbps
2 MHz	250 kbps

- Provided with 8 transmission/reception message buffers.
- Transmission/reception is allowed at ID 11 bit in standard format, and at ID 29 bit in expanded frame format.
- Specifying 0 byte to 8 bytes is allowed in message data.
- Multi-level message buffer configuration is allowed.
- CAN controller has two built-in acceptance masks. Mask settings are independently allowed for the two acceptance masks on reception IDs.
- The two acceptance masks allow reception in standard frame format and expanded frame format.
- For types of masking, all-bit comparison, all-bit masking, and partial masking with acceptance mask register 0/1, are specifiable.

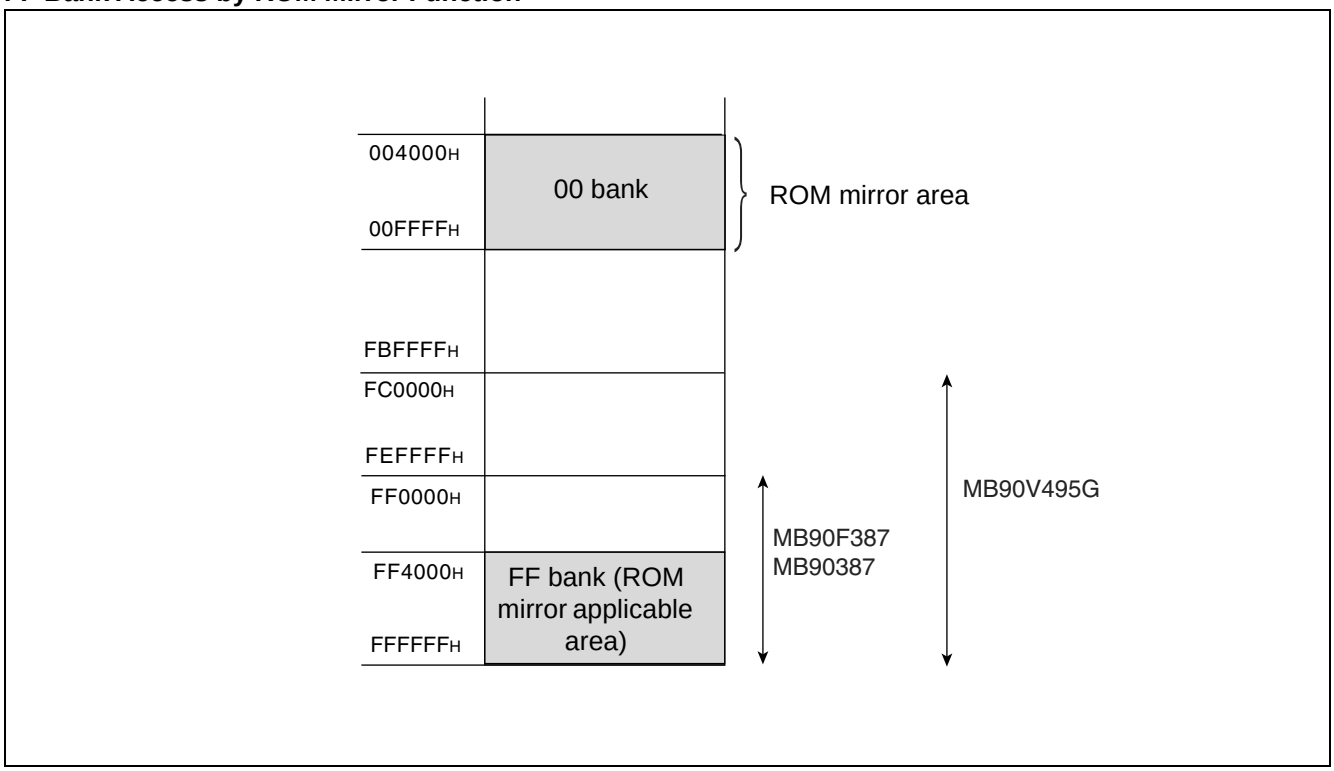
12.14 ROM Mirror Function Selection Module Outline

The ROM mirror function selection module sets the data in ROM assigned to FF bank so that the data is read by access to 00 bank.

ROM Mirror Function Selection Module Block Diagram



FF Bank Access by ROM Mirror Function



12.15 512 Kbit Flash Memory Outline

The following three methods are provided for data writing and deleting on Flash memory:

1. Parallel writer
2. Serial special-purpose writer
3. Writing/deleting by program execution

This section describes “3. Writing/deleting by program execution.”

512 Kbit Flash Memory Outline

The 512 Kbit Flash memory is allocated on FF_H bank of CPU memory map. Using the function of Flash memory interface circuit, the memory allows read access and program access from CPU.

Writing/deleting on Flash memory is performed by instruction from CPU via Flash memory interface. Because rewriting is allowed on mounted memory, modifying program and data is performed efficiently.

Features of 512 Kbit Flash Memory

- 128 K words x 8 bits/64 K words x 16 bits (16 K + 8 K + 8 K + 32 K) sector configuration
- Automatic program algorithm (Embedded Algorithm: Similar to MBM29LV200.)
- Built-in deletion pause/deletion resume function
- Detection of completed writing/deleting by data polling and toggle bits.
- Detection of completed writing/deleting by CPU interrupt.
- Deletion is allowed on a sector-by-sector basis (sectors are combined freely).
- Number of writing/deleting operations (minimum): 10,000 times
- Sector protection
- Expanded sector protection
- Temporaly sector unprotection

Note: A function of reading manufacture code and device code is not provided. These codes are not accessible by command either.

Flash Memory Writing/Deleting

- Writing and reading data is not allowed simultaneously on the Flash memory.
- Data writing and deleting on the Flash memory is performed by the processes as follows: Make a copy of program on Flash memory onto RAM. Then, execute the program copied on the RAM.

List of Registers and Reset Values in Flash Memory

Flash memory control status register (FMCS)

bit	7	6	5	4	3	2	1	0
	0	0	0	X	0	0	0	0

× : Undefined

Sector Configuration

For access from CPU, SA0 to SA3 are allocated in FF bank register.

13. Electrical Characteristics

13.1 Absolute Maximum Rating

Parameter	Symbol	Rating		Unit	Remarks
		Min	Max		
Power supply voltage*1	V_{CC}	V_{SS} – 0.3	V_{SS} + 6.0	V	
	AV_{CC}	V_{SS} – 0.3	V_{SS} + 6.0	V	$V_{CC} = AV_{CC}$*2
	AVR	V_{SS} – 0.3	V_{SS} + 6.0	V	$AV_{CC} \geq AVR$*2
Input voltage*1	V_I	V_{SS} – 0.3	V_{SS} + 6.0	V	*3
Output voltage*1	V_O	V_{SS} – 0.3	V_{SS} + 6.0	V	*3
Maximum clamp current	I_{CLAMP}	– 2.0	+ 2.0	mA	*7
Total maximum clamp current	$\Sigma \mid I_{CLAMP} \mid$	–	20	mA	*7
“L” level maximum output current	I_{OL1}	–	15	mA	Normal output*4
	I_{OL2}	–	40	mA	High-current output*4
“L” level average output current	I_{OLAV1}	–	4	mA	Normal output*5
	I_{OLAV2}	–	30	mA	High-current output*5
“L” level maximum total output current	ΣI_{OL1}	–	125	mA	Normal output
	ΣI_{OL2}	–	160	mA	High-current output
“L” level average total output current	ΣI_{OLAV1}	–	40	mA	Normal output*6
	ΣI_{OLAV2}	–	40	mA	High-current output*6
“H” level maximum output current	I_{OH1}	–	–15	mA	Normal output*4
	I_{OH2}	–	–40	mA	High-current output*4
“H” level average output current	I_{OHAV1}	–	–4	mA	Normal output*5
	I_{OHAV2}	–	–30	mA	High-current output*5
“H” level maximum total output current	ΣI_{OH1}	–	–125	mA	Normal output
	ΣI_{OH2}	–	–160	mA	High-current output
“H” level average total output current	ΣI_{OHAV1}	–	–40	mA	Normal output*6
	ΣI_{OHAV2}	–	–40	mA	High-current output*6
Power consumption	P_D	–	245	mW	
Operating temperature	T_A	–40	+105	°C	
Storage temperature	Tstg	–55	+150	°C	

*1: The parameter is based on $V_{SS} = AV_{SS} = 0.0$ V.

*2: AVcc and AVR should not exceed Vcc.

*3: V_I and V_O should not exceed Vcc + 0.3 V. However if the maximum current to/from an input is limited by some means with external components, the I_{CLAMP} rating supersedes the V_I rating.

*4: A peak value of an applicable one pin is specified as a maximum output current.

*5: An average current value of an applicable one pin within 100 ms is specified as an average output current. (Average value is found by multiplying operating current by operating rate.)

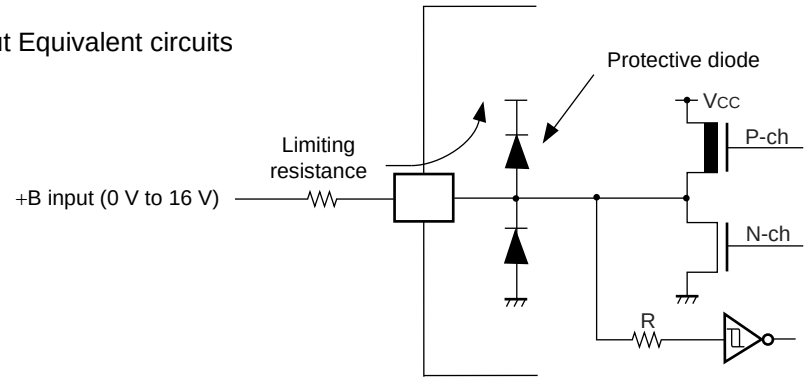
*6: An average current value of all pins within 100 ms is specified as an average total output current. (Average value is found by multiplying operating current by operating rate.)

*7:

■ Applicable to pins: P10 to P17, P20 to P27, P30 to P33, P35*, P36*, P37, P40 to P44, P50 to P57
*: P35 and P36 are MB90387S and MB90F387S only.

- Use within recommended operating conditions.
- Use at DC voltage (current).
- The +B signal should always be applied a limiting resistance placed between the +B signal and the microcontroller.
- The value of the limiting resistance should be set so that when the +B signal is applied the input current to the microcontroller pin does not exceed rated values, either instantaneously or for prolonged periods.
- Note that when the microcontroller drive current is low, such as in the power saving modes, the +B input potential may pass through the protective diode and increase the potential at the V_{CC} pin, and this may affect other devices.
- Note that if a +B signal is input when the microcontroller power supply is off (not fixed at 0 V), the power supply is provided from the pins, so that incomplete operation may result.
- Note that if the +B input is applied during power-on, the power supply is provided from the pins and the resulting supply voltage may not be sufficient to operate the power-on reset.
- Care must be taken not to leave the +B input pin open.
- Note that analog system input/output pins other than the A/D input pins (LCD drive pins, comparator input pins, etc.) cannot accept +B signal input.
- Sample recommended circuits:

• Input/Output Equivalent circuits



WARNING: Semiconductor devices can be permanently damaged by application of stress (voltage, current, temperature, etc.) in excess of absolute maximum ratings. Do not exceed these ratings.

13.2 Recommended Operating Conditions

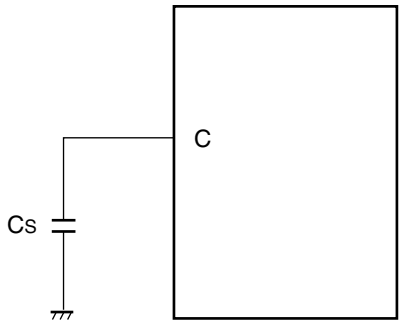
(V_{SS} = AV_{SS} = 0.0V)

Parameter	Symbol	Value			Unit	Remarks
		Min	Typ	Max		
Power supply voltage	V_{CC}	3.5	5.0	5.5	V	Under normal operation
		3.0	–	5.5	V	Retain status of stop operation
	AV_{CC}	4.0	–	5.5	V	*2
Smoothing capacitor	C_S	0.1	–	1.0	μF	*1
Operating temperature	T_A	−40	–	+105	°C	

*1: Use a ceramic capacitor, or a capacitor of similar frequency characteristics. On the Vcc pin, use a bypass capacitor that has a larger capacity than that of Cs.
Refer to the following figure for connection of smoothing capacitor Cs.

*2: AVcc is a voltage at which accuracy is guaranteed. AVcc should not exceed Vcc.

- C pin connection diagram



WARNING: The recommended operating conditions are required in order to ensure the normal operation of the semiconductor device. All of the device's electrical characteristics are warranted when the device is operated within these ranges.

Always use semiconductor devices within their recommended operating condition ranges. Operation outside these ranges may adversely affect reliability and could result in device failure.

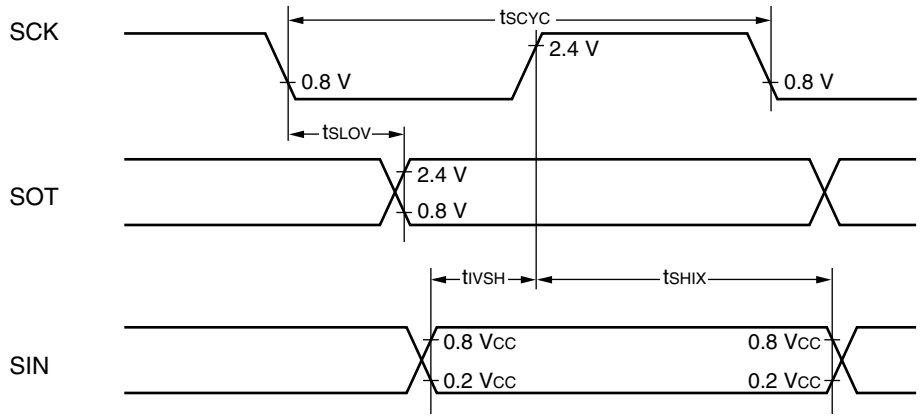
No warranty is made with respect to uses, operating conditions, or combinations not represented on the data sheet. Users considering application outside the listed conditions are advised to contact their representatives beforehand.

(V_{CC} = 5.0 V±10%, V_{SS} = AV_{SS} = 0.0 V, T_A = –40 °C to +105 °C)

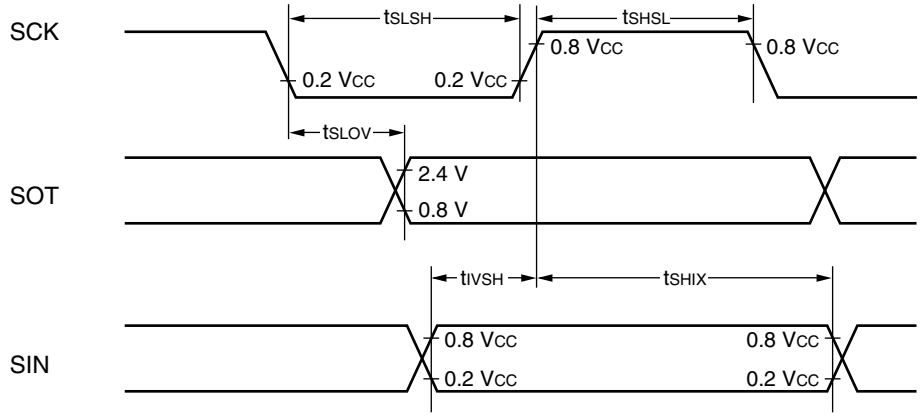
Parameter	Symbol	Pin Name	Conditions	Value			Unit	Remarks
				Min	Typ	Max		
Power supply current*	I_{CCL}	V_{CC}	V_{CC} = 5.0 V, Internally operating at 8 kHz, subclock operation, T_A = + 25°C	—	0.3	1.2	mA	MB90F387/S
				—	40	100	µA	MB90387/S
	I_{CCLS}		V_{CC} = 5.0 V, Internally operating at 8 kHz, subclock, sleep mode, T_A = + 25°C	—	10	30	µA	
	I_{CCT}		V_{CC} = 5.0 V, Internally operating at 8 kHz, watch mode, T_A = + 25°C	—	8	25	µA	
	I_{CCH}		Stopping, T_A = + 25°C	—	5	20	µA	
Input capacity	C_{IN}	Other than AV_{CC}, AV_{SS}, AVR, C, V_{CC}, V_{SS}	–	—	5	15	pF	
Pull-up resistor	R_{UP}	RST	–	25	50	100	kΩ	
Pull-down resistor	R_{DOWN}	MD2	–	25	50	100	kΩ	Flash product is not provided with pull-down resistor.

*: Test conditions of power supply current are based on a device using external clock.

• Internal shift clock mode



• External shift clock mode



13.4.5 Timer Input Timing

(V_{CC} = 4.5 V to 5.5 V, V_{SS} = 0.0 V, T_A = −40 °C to +105 °C)

Parameter	Symbol	Pin Name	Conditions	Value		Unit	Remarks
				Min	Max		
Input pulse width	t_{TIWH}	TIN0, TIN1	–	4 t_{CP} *	–	ns	
	t_{TIWL}	IN0 to IN3					

*: Refer to Clock Timing ratings for t_{CP} (internal operation clock cycle time).

13.5 A/D Converter

(V_{CC} = AV_{CC} = 4.0 V to 5.5 V, V_{SS} = AV_{SS} = 0.0 V, 3.0 V ≤ AVR − AV_{SS}, T_A = −40 °C to +105 °C)

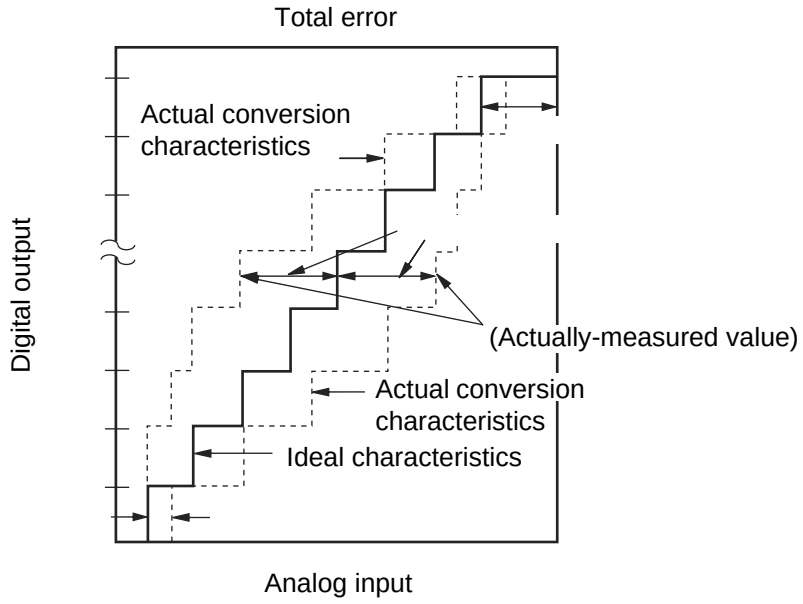
Parameter	Symbol	Pin Name	Value			Unit	Remarks
			Min	Typ	Max		
Resolution	–	–	–	–	10	bit	
Total error	–	–	–	–	± 3.0	LSB	
Nonlinear error	–	–	–	–	± 2.5	LSB	
Differential linear error	–	–	–	–	± 1.9	LSB	
Zero transition voltage	V_{OT}	AN0 to AN7	AV_{SS} − 1.5 LSB	AV_{SS} + 0.5 LSB	AV_{SS} + 2.5 LSB	V	1 LSB = (AVR − AV_{SS}) / 1024
Full-scale transition voltage	V_{FST}	AN0 to AN7	AVR − 3.5 LSB	AVR − 1.5 LSB	AVR + 0.5 LSB	V	
Compare time	–	–	66 t_{CP} *1	–	–	ns	With 16 MHz machine clock 5.5 V ≥ AV_{CC} ≥ 4.5 V
			88 t_{CP} *1	–	–	ns	With 16 MHz machine clock 4.5 V > AV_{CC} ≥ 4.0 V
Sampling time	–	–	32 t_{CP} *1	–	–	ns	With 16 MHz machine clock 5.5 V ≥ AV_{CC} ≥ 4.5 V
			128 t_{CP} *1	–	–	ns	With 16 MHz machine clock 4.5 V > AV_{CC} ≥ 4.0 V
Analog port input current	I_{AIN}	AN0 to AN7	–	–	10	µA	
Analog input voltage	V_{AIN}	AN0 to AN7	AV_{SS}	–	AVR	V	
Reference voltage	–	AVR	AV_{SS} + 2.7	–	AV_{CC}	V	
Power supply current	I_A	AV_{CC}	–	3.5	7.5	mA	
	I_{AH}	AV_{CC}	–	–	5	µA	*2
Reference voltage supplying current	I_R	AVR	–	165	250	µA	
	I_{RH}	AVR	–	–	5	µA	*2
Variation among channels	–	AN0 to AN7	–	–	4	LSB	

*1: Refer to Clock Timing on AC Characteristics.

*2: If A/D converter is not operating, a current when CPU is stopped is applicable (Vcc=AVcc=AVR=5.0 V).

13.6 Definition of A/D Converter Terms

Resolution:	Analog variation that is recognized by an A/D converter.
Linear error:	Deviation between a line across zero-transition line (“00 0000 00 0 0” ←→“00 0000 0001”) and full-scale transition line (“11 1111 11 1 0” ←→ “11 1111 1111”) and actual conversion characteristics.
Differential linear error:	Deviation of input voltage, which is required for changing output code by 1 LSB, from an ideal value.
Total error:	Difference between an actual value and an ideal value. A total error includes zero transition error, full-scale transition error, and linear error.



$$\text{Total error of digital output “N”} = \frac{V_{NT} - \{1\ \text{LSB} \times (N - 1) + 0.5\ \text{LSB}\}}{1\ \text{LSB}} \quad [\text{LSB}]$$

$$1\ \text{LSB} = (\text{Ideal value})\ \frac{AVR - AV_{SS}}{1024}\ [V]$$

V_{OT} (Ideal value) = AV_{SS} + 0.5 LSB [V]

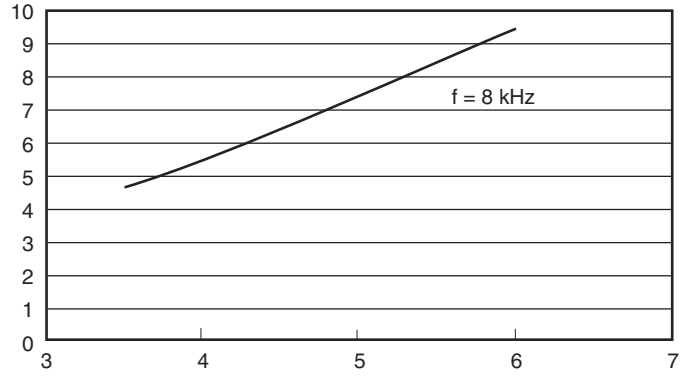
V_{FST} (Ideal value) = AVR − 1.5 LSB [V]

V_{NT}: A voltage at which digital output transits from $(N\text{-}1)_H$ to N_H.

(Continued)

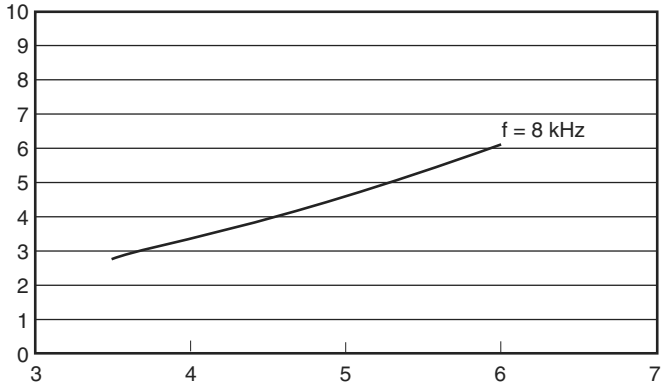
I_{CCLS} – V_{CC}

T_A = +25 °C, In external clock operation
f = Internal operating frequency



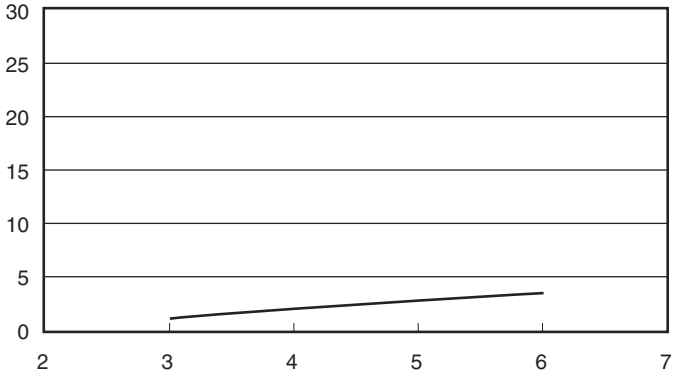
I_{CCT} – V_{CC}

T_A = +25 °C, In external clock operation
f = Internal operating frequency



I_{CCH} – V_{CC}

Stopping, T_A = +25 °C



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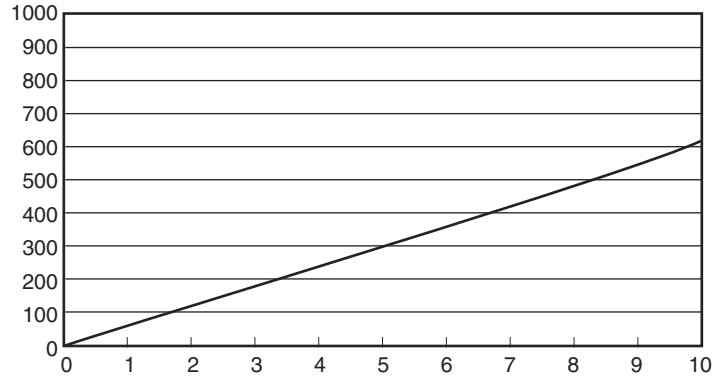
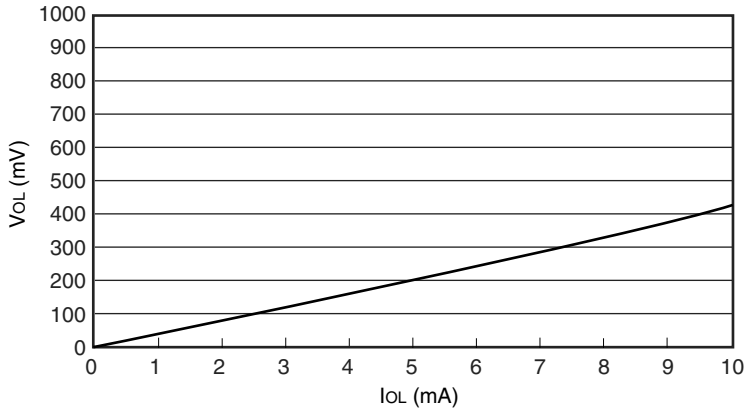
(V_{CC} - V_{OH}) – I_{OH}

T_A = +25 °C, V_{CC} = 4.5 V



V_{OL} – I_{OL}

T_A = +25 °C, V_{CC} = 4.5 V



H level input voltage/ L level input voltage
V_{IN} – V_{CC}

T_A = +25 °C